

09/940513

08/29/01

ISSUE CLASSIFICATION	
Class	Subclass

PATENT NUMBER

U.S. **UTILITY** Patent Application

O.I.P.E.

PATENT DATE

O.I.P.E.
SCANNED 22(3) O.A. 11/1

APPLICATION NO.
09/940513

CONT/PRIOR
D F

CLASS
428

SUBCLASS
117

ART UNIT	127-1-
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EXAMINER K. HAN

PPLICANTS Yasushi Sawamura
Shoji Kigoshi
Taku Hatano
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- Adhesive sheet for semiconductor connecting substrate, adhesive-backed tape for TAB, adhesive-backed tape for wire bonding connection, semiconductor connecting substrate, and semiconductor device

PTD-204
12/99

ISSUING CLASSIFICATION

ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

☐ Continued on Issue Slip Inside File Jacket

☐ **TERMINAL
DISCLAIMER**

DRAWINGS

Sheets Drwg.

Figs. Drwg.

Print Fig.

CLAIMS ALLOWED

Total Claims

Print Claim for O.G.

☐ The term of this patent subsequent to _____ (date) has been disclaimed.

☐ The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____

☐ The terminal _____ months of this patent have been disclaimed.

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

ISSUE BATCH NUMBER

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